

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ANALOG MEMS SENSORS/25/15617	
1.3 Title of PCN	ST Manufacturing Reshaping (MEMS 3): For ASIC, Qualification of Rousset 8" (FRANCE) as new FE location and Singapore for PIX deposition and new EWS Location. For MEMS, Qualification of CROLLES as new EWS Location.	
1.4 Product Category	Pls refer to impacted Products List.	
1.5 Issue date	2025-08-08	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Simone FERRI
2.1.2 Marketing Manager	Tarik SOUIBES
2.1.3 Quality Manager	Fabio BIGANZOLI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Manufacturing reshaping program	Manufacturing reshaping program	ASIC: RS8F (Rousset 8") as Front End Plant ASIC: Singapore for PIX deposition ASIC: Singapore as EWS Plant MEMS: Crolles as EWS Plant

4. Description of change

	Old	New
4.1 Description	ASIC : CR200 as Front End Plant ASIC : CR200 for PIX deposition ASIC: Catania (Italy) as EWS Plant MEMS: Agrate (Italy) as EWS Plant	ASIC: RS8F (Rousset 8") as Front End Plant ASIC: Singapore for PIX deposition ASIC: Singapore as EWS Plant MEMS: Crolles as EWS Plant
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact. The products guarantee the same quality and electrical characteristics as per current production.	

5. Reason / motivation for change

5.1 Motivation	In the frame of ST manufacturing reshaping program (refer to Corporate PCI 15383 - Early Notification), following the continuous improvement of our service and to increase production Capacity, ST Microelectronics is announcing for ASIC, qualification of Rousset 8" (FRANCE) as new FE location and Singapore for PIX deposition and new EWS Location; for MEMS, qualification of CROLLES as new EWS Location. Please be advised that the enclosed list of products and dates could be subject to change. Such modifications may occur as part of the ongoing transformation program and will be communicated as and when available. a. SCHEDULING COMMENT: Below schedule of qualification report availability and intended start of delivery refer to first product qualification.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability of change will be ensured by an internal codification
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7. Timing / schedule

7.1 Date of qualification results	2026-12-31
7.2 Intended start of delivery	2027-06-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)			
15617 Public product.pdf 15617 MEMS 3.pdf			

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	AIS25BATR	

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